



DUAL P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	RDS(ON) max	I _D T _A = +25°C
	$38m\Omega @ V_{GS} = -10V$	-5.7A
-20V	$43m\Omega$ @ $V_{GS} = -4.5V$	-5.4A
	$75m\Omega$ @ $V_{GS} = -2.5V$	-4.1A

Description

This new generation MOSFET has been designed to minimize the onstate resistance $(R_{DS(ON)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Power Management Functions
- Battery Pack
- Load Switch

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

Case: U-DFN2030-6

G2

G1

S2

S1

D1/D2

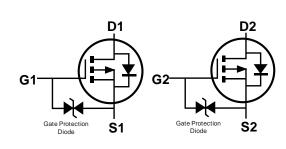
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.012 grams (Approximate)











Equivalent Circuit

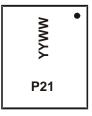
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2100UFU-7	U-DFN2030-6	3000 / Tape & Reel
DMP2100UFU-13	U-DFN2030-6	10000 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



P21 = Product Type Marking Code YYWW = Date Code Marking YY = Last Digit of Year (ex: 14 for 2014) WW = Week Code (01 to 53)

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Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			V _{DSS}	-20	V
Gate-Source Voltage			V _{GSS}	±10	V
Continuous Drain Current (Note 6) $V_{GS} = -10V$ Steady $T_A = +25^{\circ}C$ State $T_A = +70^{\circ}C$		ID	-5.7 -4.4	А	
Maximum Continuous Body Diodes Forward Current (Note 6)			Is	-2	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	-30	Α
Avalanche Current (Note 7) L = 0.1mH			I _{AS}	-15	Α
Avalanche Energy (Note 7) L = 0.1mH			E _{AS}	12	mJ

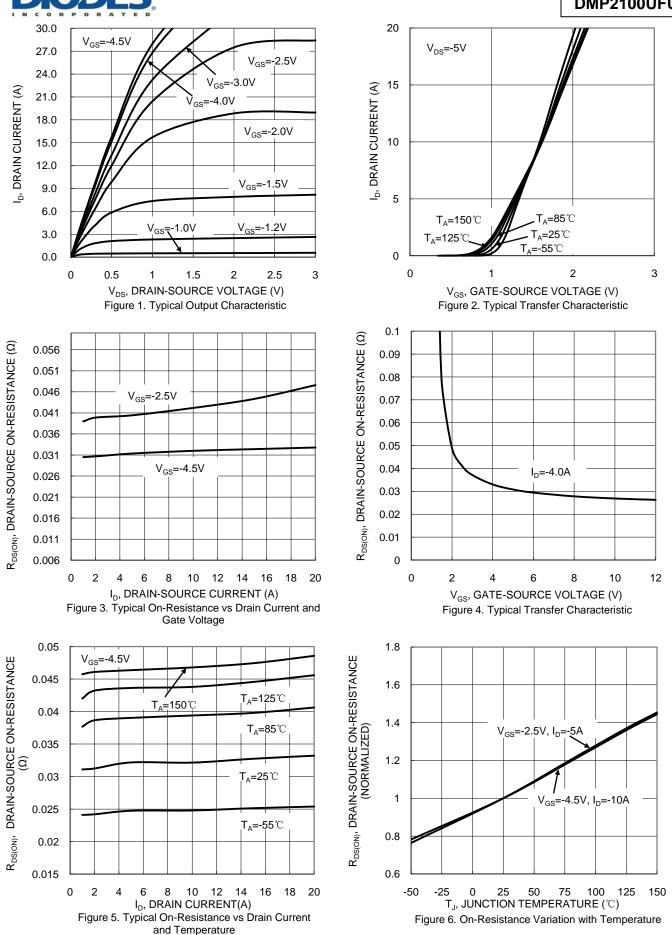
Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	P_{D}	0.9	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	138	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	P_{D}	1.9	W
Thermal Resistance, Junction to Ambient (Note 6) Steady Sta		$R_{\theta JA}$	66	°C/W
Thermal Resistance, Junction to Case		$R_{ heta JC}$	9.6	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS	_	_	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-0.3	_	-1.4	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
			25	38		$V_{GS} = -10V, I_D = -3.5A$	
Static Drain-Source On-Resistance	D	_	29	43	mΩ	$V_{GS} = -4.5V, I_D = -3A$	
Static Dialit-Source Off-Resistance	R _{DS(ON)}	_	37	75	11122	$V_{GS} = -2.5V, I_D = -1A$	
		_	47	_		$V_{GS} = -1.8V, I_D = -0.5A$	
Diode Forward Voltage	V_{SD}	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -2.9A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	_	906	_	pF	101/11/	
Output Capacitance	Coss	_	103	_	pF	V _{DS} = -10V, V _{GS} = 0V -f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	29	_	pF	1 = 1.0WHZ	
Gate Resistance	R_g	_	259	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Q_g	_	10.3	_	nC		
Total Gate Charge (V _{GS} = -10V)	Q_g	_	21.4	_	nC	V 10V I 10	
Gate-Source Charge	Q _{gs}		1.6	_	nC	$V_{DS} = -10V, I_{D} = -4A$	
Gate-Drain Charge	Q_{gd}	_	2.3	_	nC	1	
Turn-On Delay Time	t _{D(ON)}	_	70	_	ns	$V_{DS} = -10V$, $V_{GS} = -4.5V$, $R_L = 2.5\Omega$, $R_G = 3.0\Omega$	
Turn-On Rise Time	t _R	_	144	_	ns		
Turn-Off Delay Time	t _{D(OFF)}		626	_	ns		
Turn-Off Fall Time	t _F	_	396	_	ns		
Body Diode Reverse Recovery Time	t _{RR}	_	279	_	ns	I _F = -3.5A, di/dt = -100A/μs	
Body Diode Reverse Recovery Charge	Q _{rr}	_	466	_	nC	$I_F = -3.5A$, $di/dt = -100A/\mu s$	

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.



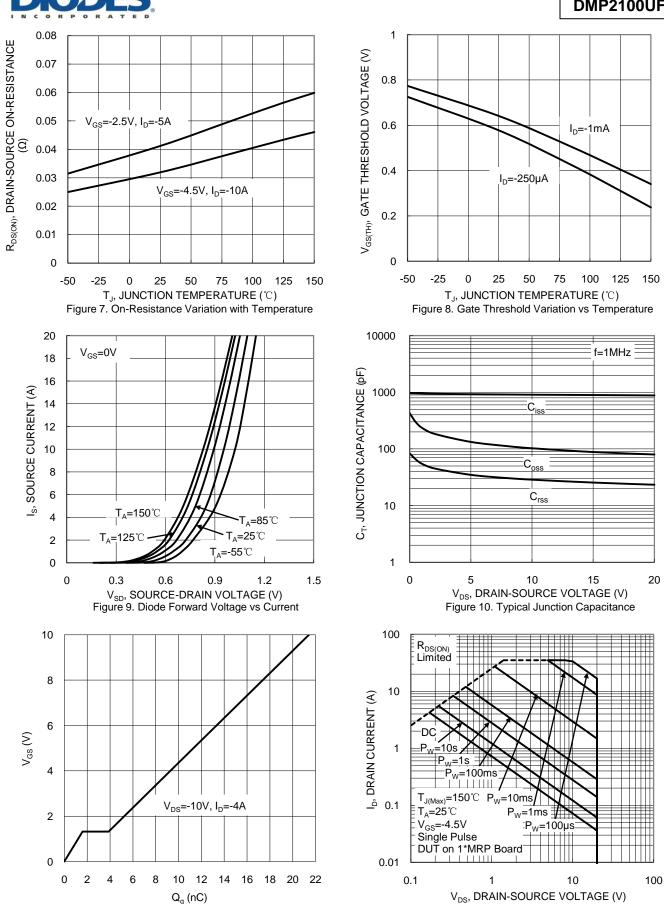


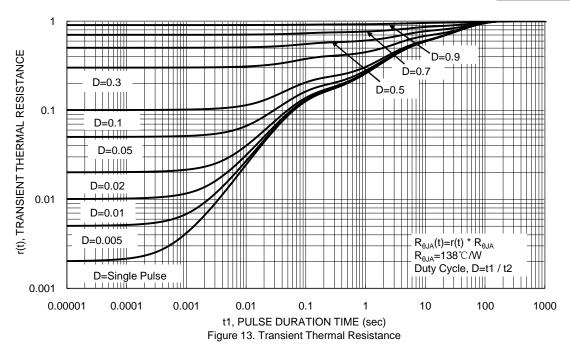
Figure 11. Gate Charge

Figure 12. SOA, Safe Operation Area

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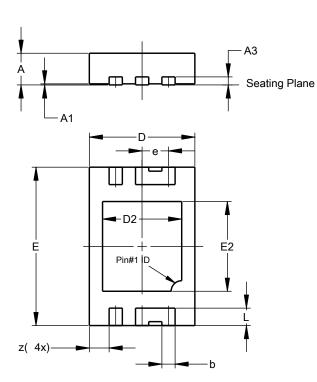






Package Outline Dimensions

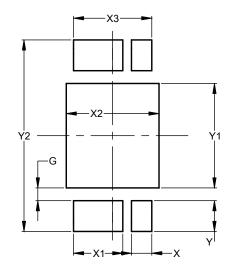
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	U-DFN2030-6 (Type B)					
Dim	Min	Max	Тур			
Α	0.55	0.65	0.60			
A1	0.00	0.05	0.02			
A3			0.15			
b	0.20	0.30	0.25			
D	1.95	2.05	2.00			
D2	1.40	1.60	1.50			
Е	2.95	3.05	3.00			
E2	1.65	1.75	1.70			
е			0.50			
L	0.28	0.38	0.33			
Z			0.375			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value		
פווטופוושוווט	(in mm)		
G	0.220		
Х	0.350		
X1	0.850		
X2	1.600		
Х3	1.350		
Y	0.530		
Y1	1.800		
Y2	3.300		



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